

EV372454208**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Serial No. 09/148,723
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner Anthony D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

TERMINAL DISCLAIMER

I, D. Brent Kenady, residing at Spokane, Washington, represent that I am the attorney of record for Micron Technology, Inc., a corporation of the state of Delaware. Micron Technology, Inc. is the owner of all right, title and interest of this U.S. Patent Application Serial No. 09/148,723, filed September 3, 1998, as evidenced by an assignment recorded November 2, 1998, Reel 9579, Frames 0391-0395 in the U.S. Patent and Trademark Office.

Micron Technology, Inc. is also the owner of all rights, title and interest in co-pending U.S. Patent Application Serial No. 10/004,172, as evidenced by an assignment recorded November 2, 1998, at Reel 9579, Frames 0391-0395, in the U.S. Patent and Trademark Office.

The evidentiary documents have been reviewed, and I certify that, to the best of assignee's knowledge and belief, title is in the assignee seeking to take this action.

Micron Technology, Inc. hereby disclaims the terminal part of any future patent granted on this U.S. Patent Application Serial No. 09/148,723 which extends beyond the expiration date of a patent granted on co-pending U.S. Patent Application Serial No. 10/004,172, and further hereby agrees that any

future patent so granted on this U.S. Patent Application Serial No. 09/148,723 shall be enforceable only for and during such period that the legal title on any patent granted on co-pending U.S. Patent Application Serial No. 10/004,172 shall be the same as the legal title to any patent issued from U.S. Patent Application Serial No. 09/148,723. This agreement is to run with any patent granted on the application and is to be binding upon the grantee of such patent and its successors or assigns.


Micron Technology, Inc. does not disclaim any terminal part of any patent granted on this 09/148,723 application prior to the expiration date of the full statutory term of a patent granted on the co-pending U.S. Patent Application Serial No. 10/004,172 in the event that it later: expires for failure to pay a maintenance fee, is held unenforceable, is found invalid by a court of competent jurisdiction, is statutorily disclaimed in whole or terminally disclaimed under 37 C.F.R. §1.321(a), has all claims canceled by a reexamination certificate, is reissued in any manner or is otherwise terminated prior to expiration of its full statutory term as presently shortened by any terminal disclaimer, except for the separation of legal title stated above.

The fee required by 37 C.F.R. §1.20(d) is submitted herewith. The Commissioner is hereby authorized to charge payment of any additional fees or credit overpayments to Deposit Account No. 23-0925.

The undersigned, D. Brent Kenady, hereby indicates that he is authorized to sign this document on behalf of the assignee, Micron Technology, Inc.

Respectfully submitted,

Dated: 6-16-04

By: 
D. Brent Kenady
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